

Ink-jet patterning of graphene by cap assisted barrier-guided CVD

Received 00th January 20xx,

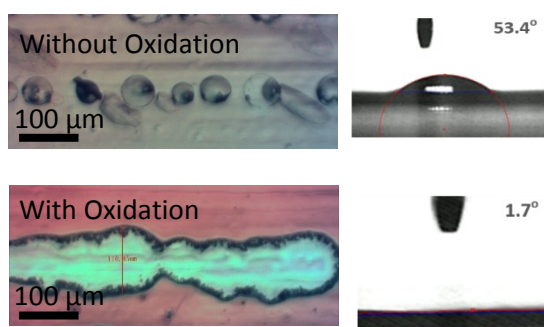
Accepted 00th January 20xx

DOI: 10.1039/x0xx00000x

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Supplementary Fig. S1

indicated that Cu was converted into Cu₂O through thermal-oxidation during the annealing process.



XRD analysis

According to XRD spectrum, the printed Al₂O₃ XRD peaks show the γ -Al₂O₃ phase at 47.48°, which indicated γ -Al₂O₃ phases present before annealing process (Figure 2(a) green line, and Figure 2(b)).

For the free flow condition as annealing with H₂ only, without spacer and cap situation, Al₂O₃ barriers were etched away (Figure (c)), and XRD peaks only present Cu crystal peaks at 43.28°, 50.40°, corresponding to (111), (200), respectively (JCPDS Copper: 04-0836)(Figure 2 blue line).

Under the annealing with Ar condition (Figure 2(a), black line and Figure 2 (d)) was to mimic the Al₂O₃ barriers annealing process with the cap and spacer condition, which is to consider the limited H₂ gas flow during the annealing process. As the Figure 2 black line and Figure (d) shown the α -Al₂O₃ present after annealed with Ar only, which may imply that the γ -Al₂O₃ can be preserved without H₂ etching and convert into a stable α -Al₂O₃ in the real condition.

Notice that Cu₂O (111), (200) (JCPDS card, no# 125678-2076) (Figure 2 blue line) phase appeared after annealing with Ar only process, and no strong Cu (111) and (200) present, which

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Electronic Supplementary Information (ESI) available: [Microscope images and complete Raman spectra]. See DOI: 10.1039/x0xx00000x